



SUPERSMART – paper-based printed electronics as environmentally friendly and cost-efficient alternative

von Simone Fränkel | Apr. 15, 2021 | General

The SUPERSMART research project funded by EIT RawMaterials has shown proof: printed electronic components such as sensors and smart labels on paper can play an essential role in building a smart environment for production, retail and logistics. Efficient and reliable...

Winner OE-A Competition 2021

von madeleine.geiling@isc.fraunhofer.de | März 31, 2021 | General

The SUPERSMART project team is proud to have been selected by the international jury as the winner of the 2021 OE-A competition within the category „Best Publicly Funded Project Demonstrator“. The SUPERSMART research project funded by EIT RawMaterials has...

Press Release published addressing ECOtronic project

von madeleine.geiling@isc.fraunhofer.de | Dez. 21, 2019 | General

Complementary to the activities in Supersmart, several institutes in Finland launched the ECOtronic project in order to transform electronic industry into a circular economy. The ECOtronic project aims to use materials that can be safely recycled, composted or...

Supersmart Flyer available

von madeleine.geiling@isc.fraunhofer.de | Juli 10, 2019 | General, News

In order to have a comprehensive overview about contents, objectives and partners of the SUPERSMART project, there is a new flyer for download available: Download:
Supersmart_Projektflyer

Presentation of SUPERSMART project at EIT Raw Materials Summit 2019

von madeleine.geiling@isc.fraunhofer.de | Mai 15, 2019 | General, Messe

Michel Glotin from Supersmart Coordinator Arkema will present first results of the Supersmart project at EIT Raw Materials Summit 2019. This summit takes place between May, 20 and May, 22 in Berlin, Germany.

Participation from VTT at AIPIA USA Summit

von madeleine.geiling@isc.fraunhofer.de | Mai 15, 2019 | General, Messe

Supersmart partner VTT will participate at AIPIA USA Summit on July, 3-4, 2019 in New Jersey. VTT will exhibit amongst other technical samples from Supersmart project in order to demonstrate technical solutions for smart paper and packaging.

Kick-Off Meeting on March 13th, 2018

von Simone Fränkel | Apr. 2, 2019 | General

On March 13th, 2018, the SUPERSMART consortium launched the project in a Kick-Off Meeting. The meeting took place in Munich and went along with the Lope-C 2018 conference. The SUPERSMART members committed themselves to upscale techno and material syntheses for...

New posts

About the project

This activity has received funding from the European Institute of Innovation and Technology (EIT). This body of the European Union receives support from the European Union's Horizon 2020 research and innovation programme.

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